## Kyoung-Tae Kim

List of Publications by Year in descending order

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#	Article	IF	CITATIONS
1	Characterization of the Current Mechanisms and Improved Leakage Current in Silver Doped Barium Strontium Titanate. , 2019, , .		О
2	Fabrication of high-aspect-ratio nanoporous high-k MTiO <inf>3</inf> (M= Ba, Sr, or) Tj ETQq0 0 0 rg 2017, , .	BT /Overloo	ck 10 Tf 50 70 0
3	Fabrication of Self-Packaged Seamless Nanoporous SU-8 Microchannels. Journal of Microelectromechanical Systems, 2015, 24, 256-258.	1.7	Ο
4	Room temperature multiferroic properties of (Fex, Sr1â^'x)TiO3 thin films. Applied Physics Letters, 2014, 105, .	1.5	16
5	Microwave characteristics of sol-gel based Ag-doped (Ba0.6Sr0.4)TiO3 thin films. Thin Solid Films, 2014, 565, 172-178.	0.8	15
6	Fabrication of an all SU-8 electrospun nanofiber based supercapacitor. Journal of Micromechanics and Microengineering, 2013, 23, 114011.	1.5	12
7	Subwavelength Direct Laser Patterning of Conductive Gold Nanostructures by Simultaneous Photopolymerization and Photoreduction. ACS Nano, 2011, 5, 1947-1957.	7.3	110
8	Fabrication and Characterization of Goldâ^'Polymer Nanocomposite Plasmonic Nanoarrays in a Porous Alumina Template. ACS Nano, 2010, 4, 2249-2255.	7.3	66
9	Characteristics of Nickel-doped Zinc Oxide thin films prepared by sol–gel method. Surface and Coatings Technology, 2008, 202, 5650-5653.	2.2	52
10	Fabrication of submicron structures in nanoparticle/polymer composite by holographic lithography and reactive ion etching. Applied Physics Letters, 2008, 93, 203509.	1.5	6
11	Ferroelectric properties of Bi3.25La0.75Ti3O12 films using HfO2 as buffer layers for nonvolatile-memory field-effect transistors. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2008, 26, 1178-1181.	0.9	6
12	Etching Characteristics of (Na0.5K0.5)NbO3Thin Films in an Inductively Coupled Cl2/Ar Plasma. Ferroelectrics, 2007, 357, 179-184.	0.3	6
13	Dielectric Properties of (Pb,Sr)TiO <sub>3</sub> Heterolayered Thin Films for Tunable Application. Ferroelectrics, 2007, 357, 211-217.	0.3	Ο
14	Etch Properties of Hf-Based High-kDielectrics Using Inductively Coupled Plasma. Ferroelectrics, 2007, 357, 41-47.	0.3	4
15	Dielectric Properties of (Na, K)NbO3Thin Films for Tunable Microwave Device Application. Ferroelectrics, 2007, 356, 166-171.	0.3	4
16	Effect of LaNiO3 electrode on microstructural and ferroelectric properties of Bi3.25Eu0.75Ti3O12 thin films. Thin Solid Films, 2007, 515, 8082-8086.	0.8	20
17	Etch damage evaluation on (Bi4â^'xLax)Ti3O12 thin films during the etch process using inductively coupled plasma sources. Materials Science in Semiconductor Processing, 2006, 9, 1108-1114.	1.9	6
18	Electrical and dielectric properties of Ce-doped Ba0.6Sr0.4TiO3 thin films. Surface and Coatings Technology, 2006, 200, 4708-4712.	2.2	35

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19	Dry etching of LaNiO3 thin films using inductively coupled plasma. Thin Solid Films, 2006, 506-507, 217-221.	0.8	5
20	Effect of lanthanides-substituted on ferroelectric properties of bismuth titanate thin films prepared by metalorganic decomposition. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2005, 118, 229-233.	1.7	18
21	The effect of Cr doping on the microstructural and dielectric properties of (Ba0.6Sr0.4)TiO3 thin films. Thin Solid Films, 2005, 472, 26-30.	0.8	81
22	Plasma etching of (Ba,Sr)TiO3 thin films using inductively coupled Cl2/Ar and BCl3/Cl2/Ar plasma. Thin Solid Films, 2005, 475, 86-90.	0.8	17
23	Characterization of BLT thin films using MgO buffer layer for MFIS-FET. Thin Solid Films, 2005, 475, 166-170.	0.8	12
24	The etching properties of MgO thin films in Cl2/Ar gas chemistry. Thin Solid Films, 2005, 475, 313-317.	0.8	11
25	Characterization of ferroelectric Bi3.25La0.75Ti3O12 thin films prepared by metal organic decomposition method. Thin Solid Films, 2005, 478, 6-12.	0.8	21
26	Correlation between dielectric properties and strain in Pb0.5 Sr0.5TiO3 thin films prepared by using the sol–gel method. Surface and Coatings Technology, 2005, 190, 190-194.	2.2	13
27	The etching properties of Al2O3 thin films in N2/Cl2/BCl3 and Ar/Cl2/BCl3 gas chemistry. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2005, 118, 201-204.	1.7	20
28	Dry etching of (Ba,Sr)TiO3 thin films using an inductively coupled plasma. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2005, 23, 894-897.	0.9	6
29	Dry etching of (Pb,Sr)TiO3 thin films using inductively coupled plasma. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2005, 23, 890-893.	0.9	0
30	Dielectric properties of highly (100) oriented (Pb[sub 0.5],Sr[sub 0.5])TiO[sub 3] thin films grown on Si with MgO buffer layer. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2004, 22, 2615.	1.6	5
31	Etching mechanism of MgO thin films in inductively coupled Cl2â •Ar plasma. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2004, 22, 2101-2106.	0.9	19
32	Ferroelectric properties of lanthanide-doped Pb(Zr0.6,Ti0.4)O3 thin films prepared by using a sol-gel method. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2004, 22, 1743-1745.	0.9	6
33	Etching properties of lead–zirconate–titanate thin films in Cl2/Ar and BCl3/Ar gas chemistries. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2004, 22, 1519-1523.	0.9	9
34	Effect of thickness on ferroelectric properties of Bi3.25La0.75Ti3O12 thin films on Pt/Ti/SiO2/Si substrates. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2004, 22, 1315-1318.	0.9	8
35	(Pb,Sr)TiO3 thin films etching characteristics using inductively coupled plasma. Thin Solid Films, 2004, 447-448, 688-692.	0.8	2
36	Dielectric properties of highly (100) oriented (Pb0.5, Sr0.5)TiO3 thin films grown on LaNiO3 electrodes. Thin Solid Films, 2004, 447-448, 651-655.	0.8	21

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37	Structural and electrical properties of metal-ferroelectric-insulator-semiconductor field-effect transistors using a Pt/Bi3.25La0.75Ti3O12/CeO2/Si structure. Thin Solid Films, 2004, 447-448, 322-326.	0.8	9
38	Electrical properties of Bi4â^'xEuxTi3O12 (BET) thin films after etching in inductively coupled CF4/Ar plasma. Thin Solid Films, 2004, 447-448, 337-342.	0.8	7
39	Etching mechanism of Bi4â^'xLaxTi3O12 films in Ar/Cl2 inductively coupled plasma. Thin Solid Films, 2004, 447-448, 343-348.	0.8	16
40	Effect of Bi4Ti3O12 seeding layer on the structural and ferroelectric properties of Bi3.25La0.75Ti3O12 thin films fabricated by a metalorganic decomposition method. Thin Solid Films, 2004, 447-448, 413-417.	0.8	3
41	Etching Mechanism of Pb(Zr,Ti)O3Thin Films in Cl2/Ar Plasma. Plasma Chemistry and Plasma Processing, 2004, 24, 13-28.	1.1	13
42	Etching mechanisms of (Ba,Sr)TiO3 thin films in CF4/Ar inductively coupled plasma. Microelectronic Engineering, 2004, 71, 54-62.	1.1	13
43	Effect of bismuth excess on the crystallization of Bi3.25La0.75Ti3O12 thin films on Pt/Ti/SiO2/Si substrates. Microelectronic Engineering, 2004, 71, 266-271.	1.1	16
44	Study on the etching damage characteristics of PZT thin films after etching in Cl-based plasma. Microelectronic Engineering, 2004, 71, 294-300.	1.1	9
45	Etching mechanism of (Pb,Sr)TiO3 thin films for DRAM application using Cl2/Ar inductively coupled plasma. Vacuum, 2004, 74, 485-489.	1.6	4
46	Low temperature synthesis and ferroelectric properties of (117)-oriented Bi3.25La0.75Ti3O12 thin films on LaNiO3 electrodes. Vacuum, 2004, 74, 665-670.	1.6	7
47	Characteristics of La0.5Sr0.5CoO3 thin films fabricated by a simple metal-organic decomposition technique. Vacuum, 2004, 74, 671-675.	1.6	5
48	Etching characteristics and mechanism of Pb(Zr,Ti)O3 thin films in CF4/Ar inductively coupled plasma. Vacuum, 2004, 75, 321-329.	1.6	15
49	Improvement in ferroelectric properties of Pt/PZT/Pt capacitors etched as a function of Ar/O2 gas mixing ratio into Cl2/CF4 plasma. Thin Solid Films, 2004, 459, 71-75.	0.8	6
50	Etching characteristic and mechanism of BST thin films using inductively coupled Cl2/Ar plasma with additive CF4 gas. Thin Solid Films, 2004, 459, 127-130.	0.8	8
51	The effect of orientation on structure and ferroelectric properties of Bi3.25La0.75Ti3O12 thin films. Surface and Coatings Technology, 2004, 177-178, 770-773.	2.2	13
52	Electrical conduction behavior of ferroelectric Bi3.25La0.75Ti3O12 thin films prepared by a metalorganic decomposition method. Surface and Coatings Technology, 2004, 177-178, 774-778.	2.2	7
53	The effects of drying temperature on the crystallization of YMnO3 thin films prepared by sol-gel method using alkoxides. Journal of the European Ceramic Society, 2004, 24, 2613-2617.	2.8	32
54	Characteristics of Pt/Bi3.25La0.75Ti3O12/ZrO2/Si structures using ZrO2 as buffer layers for ferroelectric-gate field-effect transistors. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2004, 22, 1739-1742.	0.9	5

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55	Dry etching characteristics of (Ba0.6,Sr0.4)TiO3 thin films in high density CF4/Ar plasma. Surface and Coatings Technology, 2003, 171, 273-279.	2.2	21
56	Ferroelectric properties of Pb(Zr,Ti)O3 heterolayered thin films for FRAM applications. Microelectronic Engineering, 2003, 66, 662-669.	1.1	18
57	Structure and dielectric properties of Bi-doped Ba0.6Sr0.4TiO3 thin films fabricated by sol–gel method. Microelectronic Engineering, 2003, 66, 835-841.	1.1	46
58	Plasma-induced damage in PZT thin films etched by inductively coupled plasma. Thin Solid Films, 2003, 435, 222-226.	0.8	20
59	Etch characteristics of (Pb,Sr)TiO3 thin films using CF4/Ar inductively coupled plasma. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2003, 21, 1616-1619.	0.9	3
60	Etch characteristics of Bi4â^'xEuxTi3O12 (BET) thin films using inductively coupled plasma. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2003, 21, 1475-1481.	0.9	1
61	Large remanent polarization of cerium-modified bismuth–titanate thin films for ferroelectric random access memories. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2003, 21, 1376-1380.	0.9	15
62	Study of damage reduction of (Ba0.6,Sr0.4)TiO3 thin films etched in Ar/CF4 plasmas. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2003, 21, 1469-1474.	0.9	8
63	Reduction of etching damage in lead–zirconate–titanate thin films with inductively coupled plasma. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2003, 21, 1563-1567.	0.9	8
64	EFFECT OF GRAIN SIZE ON THE FERROELECTRIC PROPERTIES OF Bi3.25La0.75Ti3O12 Thin Films. International Journal of Modern Physics B, 2002, 16, 4469-4474.	1.0	9
65	The effect of Eu substitution on the ferroelectric properties of Bi4Ti3O12 thin films prepared by metal–organic decomposition. Thin Solid Films, 2002, 422, 230-234.	0.8	48
66	Recovery of plasma-induced damage in PZT thin film with O2 gas annealing. Thin Solid Films, 2001, 398-399, 448-453.	0.8	23
67	Characterization of lead zirconate titanate heterolayered thin films prepared on Pt/Ti/SiO2/Si substrate by the sol–gel method. Thin Solid Films, 2000, 372, 45-49.	0.8	20
68	Comparison of the electrical properties for etched and as-deposited BLT thin films. , 0, , .		0